

Specification GB200 Cold Plate

P/N	GB200 Cold Plate
Platform	GB200
Type	Grace Blackwell Superchip
Architecture	2x Blackwell GPU + Grace CPU
TDP(W)	2x1200W GPU +300W CPU
Total TDP(W)	2700W
Liquid Cooling module Size (WxDxH)	189.5 x 270.4 x 28.5 mm
Liquid Cooling module Weight(KG)	2.9 KG
Liquid coolant	PG25
Quick connector	CEJN UQD04
Liquid Tube Material	Stainless steel
Inlet Flow Temperature	45
Inlet Flow Rate of Liquid	1.8 LPM
Liquid pressure drop	<10 psi



GB200 Cold Plate

Key Features

- Cooling capacity : 2700W
- Compatible with DI Water/PG25 coolant
- Suitable for GB200 Superchip server and 1U chassis
- Uses UQD connectors and stainless steel corrugated tubing

Applications



HPC



AI

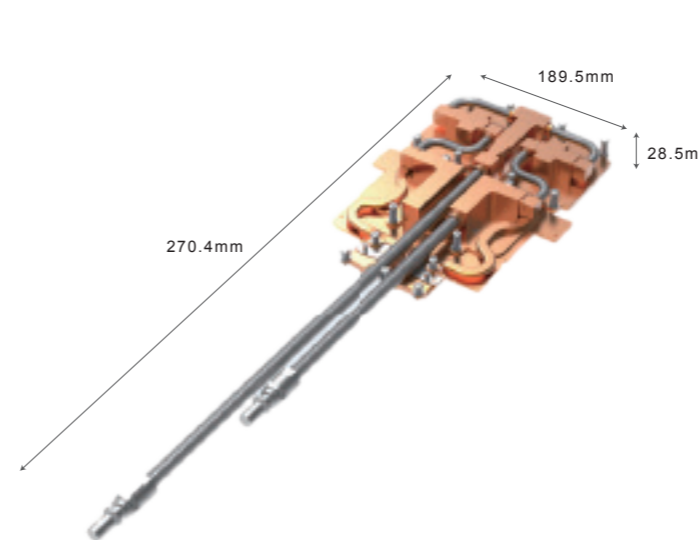


Deep Learning Training



Data Analytics

Dimension Details



For more product information and sales inquiries :

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